

Title (en)

TFT, method of manufacturing the TFT, flat panel display having the TFT, and method of manufacturing the flat panel display

Title (de)

TFT, Herstellungsverfahren für einen TFT, Flachbildschirm unter Verwendung des TFT und Methode zur Herstellung des Flachbildschirms

Title (fr)

TFT, procédé de fabrication de TFT, écran plat l'utilisant et procédé de fabrication de l'écran plat.

Publication

**EP 1598860 A2 20051123 (EN)**

Application

**EP 05104136 A 20050518**

Priority

KR 20040036635 A 20040522

Abstract (en)

A thin film transistor (TFT) including a semiconductor film that may be simply patterned, a method of manufacturing the TFT, a flat panel display (FPD) including the TFT, and a method of manufacturing the FPD. The TFT includes a gate electrode, source and drain electrodes electrically insulated from the gate electrode, and a semiconductor film electrically insulated from the gate electrode and including source and drain regions coupled to the source and drain electrodes, respectively, and a channel region coupling the source and drain regions. The semiconductor film has a groove that isolates the channel region from an adjacent TFT.

IPC 1-7

**H01L 21/336**; **H01L 29/786**; **H01L 51/40**; **H01L 21/84**; **H01L 27/12**

IPC 8 full level

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CPC (source: EP KR US)

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Cited by

US9991293B2; US9923000B2; US10170500B2; US11043509B2

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**EP 1598860 A2 20051123**; **EP 1598860 A3 20070110**; CN 100565925 C 20091202; CN 1783515 A 20060607; JP 2005340771 A 20051208; KR 100544144 B1 20060123; KR 20050111487 A 20051125; US 2005258487 A1 20051124; US 7442960 B2 20081028

DOCDB simple family (application)

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